



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-04-11
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Antonella Lanzafame	Representative title	APMSMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			

Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
VN9D5D20FTR	M040*XV67AEM	A	MU1A	2025-04-11
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	150	mg	Each	ECOPACK® 3
Identity	Authority			
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
3	260	3	
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0

Package designator	Package size	Number of instances	Shape
QFN	6x6	32	gull wing
Comment			
Comment	R040 VFQFPN 6X6X1 32 MIXPLANT RINGCUT		

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	Response
1 - Product(s) meets EU ELV requirements without any exemptions	true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Exemption Id.	Description

QueryList : California Prop65 list, dated 3rd January 2025	Response		
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen	false		
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen	true		
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.055	alloy	367

QueryList :Customer	Response
QUERY	Response

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014	Response			
QUERY	Response			
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products	false			
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products	false			
Hazardous substance				
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE
0	0	0	0	0

QueryList : REACH-21st January 2025	Response			
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	true			
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH	true			
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Tin, Tungsten,

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	false

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true

QueryList: EU Ship Recycling Regulation No. 1257/2013	Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	False

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene, Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True



Material Composition Declaration :						Mfr Item Name	M040*XV67AEM			150.0020		6999999.0	1000009.0
note : Substance present with less 0.001mg will not be declared in this document													
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die	M-011 Other inorganic materials	4.428	mg	supplier	die	Silicon(Si)	7440-21-3		3.701	mg	835818	24673	
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.137	mg	30939	913	
				supplier	metallisation	Copper(Cu)	7440-50-8		0.065	mg	14679	433	
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.055	mg	12421	367	
				supplier	metallisation	Silver(Ag)	7440-22-4		0.023	mg	5194	153	
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.020	mg	4517	133	
				supplier	metallisation	Tungsten(W)	7440-33-7		0.279	mg	63008	1860	
				supplier	metallisation	Vanadium(V)	7440-62-2		0.004	mg	903	27	
				supplier	Passivation	Silicon nitride(Si3N4)	12033-89-5		0.026	mg	5872	173	
				supplier	passivation	Silicon oxide(SiO2)	7631-86-9		0.118	mg	26649	787	
Leadframe	M-004 Copper and its alloys	44.225	mg	supplier	alloy	Copper(Cu)	7440-50-8		40.751	mg	921447	271673	
				supplier	alloy	Iron (Fe)	7439-89-6		0.717	mg	16213	4780	
				supplier	alloy	Iron phosphide	26508-33-8		0.167	mg	3776	1113	
				supplier	alloy	Zinc(Zn)	7440-66-6		0.053	mg	1198	353	
				supplier	to be defined	Tin(Sn)	7440-31-5		1.494	mg	33782	9960	
				supplier	metallization	Silver(Ag)	7440-22-4		1.043	mg	23584	6953	
Die attach	M-011 Other inorganic materials	1.507	mg	supplier	glue	Silver(Ag)	7440-22-4		1.302	mg	863968	8680	
				supplier	glue	phenolic Resin	9003-35-4		0.068	mg	45123	453	
				supplier	glue	Hexanediol diglycidyl ether	16096-31-4		0.068	mg	45123	453	
				supplier	glue	Bisphenol F type epoxy resin	9003-36-5		0.008	mg	5309	53	
				supplier	glue	Epoxy Cresol Novolac	29690-82-2		0.053	mg	35169	353	
				supplier	glue	Epoxyde bisphenol A	25068-38-6		0.008	mg	5309	53	
Bonding wires	M-004 Copper and its alloys	0.573	mg	supplier	wire	Copper(Cu)	7440-50-8		0.573	mg	1000000	3820	
Bonding wires 2	M-004 Copper and its alloys	0.493	mg	supplier	wire	Copper(Cu)	7440-50-8		0.493	mg	1000000	3287	
Encapsulation	M-011 Other inorganic materials	96.843	mg	supplier	mold compound	Silica vitreous	60676-86-0		85.221	mg	879991	568140	
				supplier	mold compound	Biphenyl epoxy	85954-11-6		4.842	mg	49998	32280	
				supplier	mold compound	Phenolic resin	205830-20-2		3.777	mg	39001	25180	
				supplier	mold compound	Epoxy type resin	proprietary		1.937	mg	20001	12913	
				supplier	mold compound	Carbon black	1333-86-4		0.194	mg	2003	1293	
				supplier	mold compound	other	proprietary		0.872	mg	9004	5813	
Connections coating	Solder	1.933	mg	supplier	solder alloy	Tin(Sn)	7440-31-5		1.933	mg	1000000	12887	